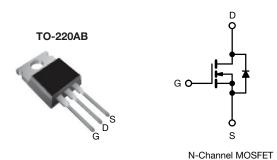


Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	250			
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	2.0		
Q _g max. (nC)	8.2			
Q _{gs} (nC)	1.8			
Q _{gd} (nC)	4.5			

Single

FEATURES

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF614PbF

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	250	V	
Gate-source voltage			V_{GS}	± 20	1 v	
Continuous drain current	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	1-	2.7	А	
		T _C = 100 °C	I _D	1.7		
Pulsed drain current a			I _{DM}	8.0		
Linear derating factor				0.29	W/°C	
Single pulse avalanche energy b			E _{AS}	61	mJ	
Repetitive avalanche current a			I _{AR}	2.7	А	
Repetitive avalanche energy ^a			E _{AR}	3.6	mJ	
Maximum power dissipation	T _C = 25 °C		P_D	36	W	
Peak diode recovery dV/dt ^c			dV/dt	4.8	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^d	For	10 s		300		
Mounting torque	6.22.04	0.00 - 140		10	lbf ⋅ in	
	6-32 or M3 screw		Ţ.	1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 13 mH, R_q = 25 Ω , I_{AS} = 2.7 A (see fig. 12)
- c. $I_{SD} \le 2.7$ A, $dI/dt \le 65$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C
- d. 1.6 mm from case

Configuration



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	3.5	

SPECIFICATIONS (T _J = 25 °C, t	ınless otherw	ise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•	•	
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		250	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.39	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		-	4.0	٧
Gate-source leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zana anto coltano durio coment		V _{DS} = 250 V, V _{GS} = 0 V		-	-	25	μА
Zero gate voltage drain current	I _{DSS}	V _{DS} = 200 V, \	V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C		-	250	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 1.6 A ^b	-	-	2.0	Ω
Forward transconductance	g _{fs}	V _{DS} = 5	0 V, I _D = 1.6 A ^b	0.90	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 V$,		-	140	-	pF
Output capacitance	C _{oss}	V _I	$V_{DS} = 25 \text{ V},$		42	-	
Reverse transfer capacitance	C _{rss}	f = 1.0	MHz, see fig. 5	-	9.6	-	1
Total gate charge	Qg			-	-	8.2	nC
Gate-source charge	Q_{gs}	V _{GS} = 10 V	$I_D = 2.7 \text{ A}, V_{DS} = 200 \text{ V}$ see fig. 6 and 13 b	-	-	1.8	
Gate-drain charge	Q_{gd}		See lig. 6 and 16	-	-	4.5	
Turn-on delay time	t _{d(on)}			-	7.0	-	
Rise time	t _r	V_{DD} = 125 V, I_D = 2.7 A, R_g = 24 Ω , R_D = 45 Ω , see fig. 10 ^b		-	7.6	-	ns ns
Turn-off delay time	t _{d(off)}			-	16	-	
Fall time	t _f			-	7.0	-	
Gate input resistance	R_g	f = 1 MHz, open drain		2.4	-	14.7	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	- nH
Internal source inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristic	cs	1					
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2.7	A
Pulsed diode forward current ^a	I _{SM}			-	-	8.0	
Body diode voltage	V _{SD}	T _J = 25 °C, I _S = 2.7 A, V _{GS} = 0 V ^b		-	-	2.0	V
Body diode reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = 2.7 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}^b$		-	190	390	ns
Body diode reverse recovery charge	Q _{rr}			-	0.64	1.3	μC
Forward turn-on time	t _{on}	Intrinsic turn	on is do	s dominated by L _S and L _D)			

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300~\mu s;~duty~cycle \leq 2~\%$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

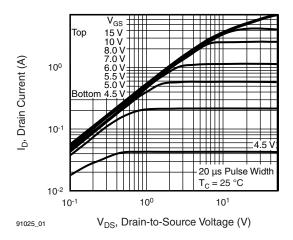


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

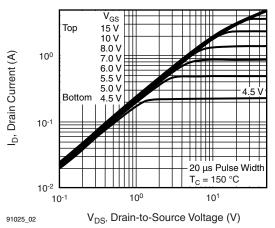


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

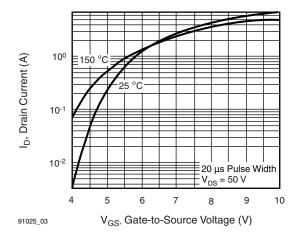


Fig. 3 - Typical Transfer Characteristics

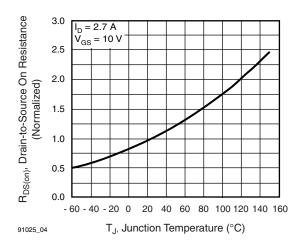


Fig. 4 - Normalized On-Resistance vs. Temperature

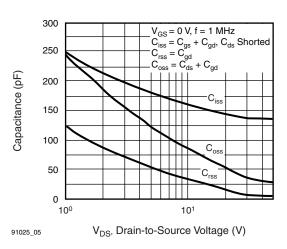


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

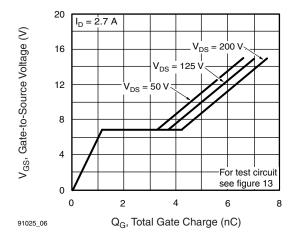


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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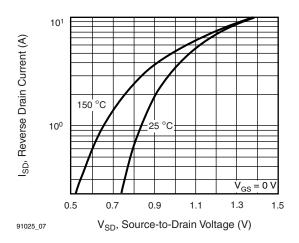


Fig. 7 - Typical Source-Drain Diode Forward Voltage

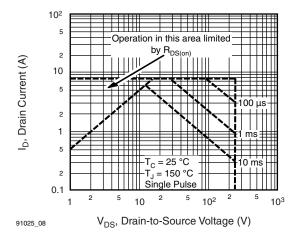


Fig. 8 - Maximum Safe Operating Area

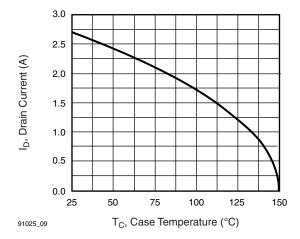


Fig. 9 - Maximum Drain Current vs. Case Temperature

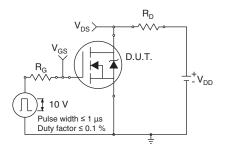


Fig. 10a - Switching Time Test Circuit

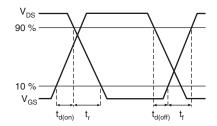


Fig. 10b - Switching Time Waveforms



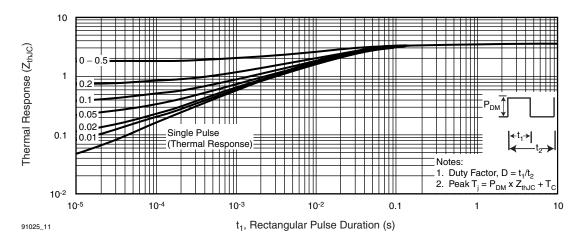


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

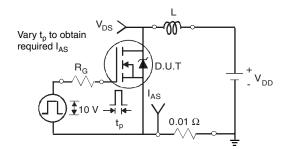


Fig. 12a - Unclamped Inductive Test Circuit

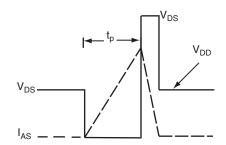


Fig. 12b - Unclamped Inductive Waveforms

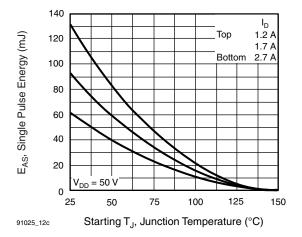
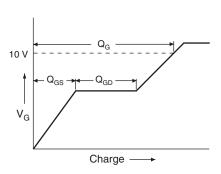


Fig. 12c - Maximum Avalanche Energy vs. Drain Current







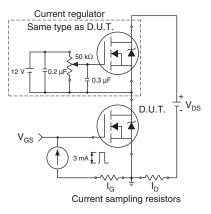
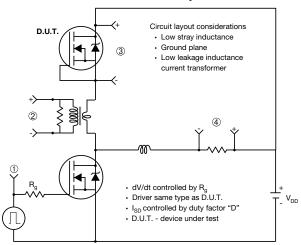


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



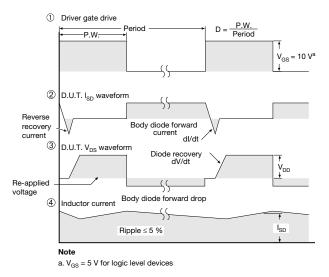


Fig.14 - For N-Channel

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